

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|---------------------|
| S1 | 695 | etch\$3 same (without abscense "no" exclud\$3) near2 (oxygen "O. sub.2" O2) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 15:52 |
| S2 | 10 | (etch\$3 same (without abscense "no" exclud\$3) near2 (oxygen "O. sub.2" O2)) same (BCB Silk Flare polysiloxane siloxane (si silicon) near organic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:19 |
| S3 | 17 | (etch\$3 same (without abscense "no" exclud\$3) near2 (oxygen "O. sub.2" O2)) same (silsesquioxane HSQ orthosilicate TEOS silane) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:50 |
| S4 | 102 | etch\$3 same (absence absent exclusion) near2 (oxygen "O. sub.2" O2) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:50 |

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| S5 | 5 | (etch\$3 same (absence absent exclusion) near2 (oxygen "O.sub.2" O2)) same (silsesquioxane HSQ orthosilicate TEOS silane BCB Silk Flare polysiloxane siloxane (si silicon) near organic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:54 |
| S6 | 24 | (etch\$3 same (absence absent exclusion) near2 (oxygen "O.sub.2" O2)) and (silsesquioxane HSQ orthosilicate TEOS silane BCB Silk Flare polysiloxane siloxane (si silicon) near organic) not ((etch\$3 same (absence absent exclusion) near2 (oxygen "O.sub.2" O2)) same (silsesquioxane HSQ orthosilicate TEOS silane BCB Silk Flare polysiloxane siloxane (si silicon) near organic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:54 |
| S7 | 1334 | etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 16:40 |
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| S8 | 13 | (etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 16:38 |
| S9 | 18 | (etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) with (oxygen "O.sub.2" O2)) not ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 16:35 |

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| S10 | 252 | (etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) and ((absence absent free without "no" exclu\$4) with (oxygen "O.sub.2" O2)) not (((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2))) ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) with (oxygen "O.sub.2" O2)) not ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/11/12 14:17 |
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| | | \$4) near2 (oxygen "O.sub.2" O2)))) | | | | |
| S11 | 459 | (etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) and ((absence absent free without "no" exclu\$4) same (oxygen "O.sub.2" O2)) not (((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2))) ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) with (oxygen "O.sub.2" O2)) not ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/19 17:40 |

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|-----|----|---|---|----|----|---------------------|
| | | nitrogen)) same ((absence absent free without "no" exclu \$4) near2 (oxygen "O.sub.2" O2)))) | | | | |
| S12 | 93 | (etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) and ((absence absent free without "no" exclu\$4) near2 (oxygen "O. sub.2" O2)) not (((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu \$4) near2 (oxygen "O.sub.2" O2))) ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) with (oxygen "O. sub.2" O2)) not ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 16:40 |

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| | | orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2)))) | | | | |
| S13 | 39 | etch\$3 with (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen) and ((absen\$2 free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2)) not (((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) near2 (oxygen "O.sub.2" O2))) ((etch\$3 same (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu\$4) with (oxygen "O.sub.2" O2)) not ((etch\$3 same | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 16:46 |

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| | | (low-k "low k" BCB Silk Flare polysiloxane silsesquioxane HSQ orthosilicate TEOS silane siloxane (si silicon) near (polymer organic)) same (N2 "N.sub.2" nitrogen)) same ((absence absent free without "no" exclu \$4) near2 (oxygen "O.sub.2" O2)))) | | | | |
| S14 | 0 | (tetraethylorthosilane teos) near polysiloxane | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:11 |
| S15 | 30 | (tetraethylorthosilane teos) with polysiloxane | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/11/12 14:18 |
| S16 | 95 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass) with polysiloxane | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:11 |
| S17 | 14 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass) near polysiloxane | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/11/12 14:19 |

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| S18 | 2 | (tetraethylorthosilane teos) near4 polysiloxane | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:15 |
| S19 | 0 | (tetraethylorthosilane teos) near6 polysiloxane not ((tetraethylorthosilane teos) near4 polysiloxane) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:15 |
| S20 | 8 | (tetraethylorthosilane teos) near10 polysiloxane not ((tetraethylorthosilane teos) near4 polysiloxane) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:19 |
| S21 | 12 | (tetraethylorthosilane teos) near20 polysiloxane not (((tetraethylorthosilane teos) near4 polysiloxane) ((tetraethylorthosilane teos) near10 polysiloxane not ((tetraethylorthosilane teos) near4 polysiloxane))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:22 |

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| S22 | 11 | (tetraethylorthosilane teos) with polysiloxane not (((tetraethylorthosilane teos) near4 polysiloxane) ((tetraethylorthosilane teos) near10 polysiloxane not ((tetraethylorthosilane teos) near4 polysiloxane)) ((tetraethylorthosilane teos) near20 polysiloxane not (((tetraethylorthosilane teos) near4 polysiloxane) ((tetraethylorthosilane teos) near10 polysiloxane not ((tetraethylorthosilane teos) near4 polysiloxane)))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:26 |
| S23 | 14 | (tetraethylorthosilane teos) near dielectric adj constant | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/02/19 03:26 |
| S24 | 271 | (contact adj hole via) with temperature near (profile gradient variation chang\$3) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 17:55 |
| S25 | 39 | (contact adj hole via) near2 temperature near2 (profile gradient variation chang\$3) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:14 |

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| S26 | 0 | (contact adj hole via) near2 temperature near2 ((top opening) and bottom) and etch \$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:15 |
| S27 | 34584 | (contact adj hole via) and temperature and ((top opening) and bottom) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:16 |
| S28 | 1020 | (contact adj hole via) same temperature same ((top opening) and bottom) and etch \$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:34 |
| S29 | 58 | (contact adj hole via) with temperature with ((top opening) and bottom) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:16 |
| S30 | 58 | ((contact adj hole via) with temperature with ((top opening) and bottom) and etch\$3) not ((contact adj hole via) near2 temperature near2 (profile gradient variation chang\$3) and etch\$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/08 18:17 |

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| S31 | 159 | (contact adj hole via) same temperature same ((top opening) and sidewall and bottom) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:34 |
| S32 | 17 | (contact adj hole via) same temperature with ((top opening) and sidewall and bottom) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/08 18:35 |
| S33 | 3 | (contact adj hole via) near2 temperature with ((top opening) and bottom) and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/09 10:21 |
| S34 | 1 | ("20010026952").PN. | US-PGPUB; USOCR | OR | OFF | 2003/05/22 11:17 |
| S35 | 1 | PCT/DE99/02927 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:25 |
| S36 | 1 | "198 43 624.6" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:19 |

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| S37 | 0 | "1999DE-198 43 624" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:19 |
| S38 | 0 | "1999DE 198 43 624" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:19 |
| S39 | 0 | "198 43 624" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:20 |
| S40 | 1727230 | "198" "43" "624".pran. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:21 |
| S41 | 0 | "198 43 624".pran. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:21 |
| S42 | 1 | "198 43 624.6".pran. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:21 |

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| S43 | 0 | "19843624".pran. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:21 |
| S44 | 1 | "PCT/DE99/02927" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:23 |
| S45 | 1 | "1999DE-198 43 624.6" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:24 |
| S46 | 532 | englehardt | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:25 |
| S47 | 0 | englehardt near manfred | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:25 |
| S48 | 2 | englehardt and manfred | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:27 |

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| S49 | 128 | engelhardt and manfred | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:00 |
| S50 | 78 | engelhardt near manfred | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:28 |
| S51 | 9 | (engelhardt near manfred) and integrated.ti. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:36 |
| S52 | 69 | (engelhardt near manfred) not ((engelhardt near manfred) and integrated.ti.) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 11:36 |
| S53 | 6 | engelhardt and PCT/DE99?????? | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2003/05/22 12:01 |
| S54 | 14 | etch\$3 with (contact adj hole via) with temperature with (gradient profile) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/24 12:45 |

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| S55 | 0 | etch\$3 with (contact adj hole via) with temperature near (bottom and sidewall) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 18:55 |
| S56 | 0 | etch\$3 with (contact adj hole via) with temperature near2 (bottom and sidewall) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 18:55 |
| S57 | 2 | etch\$3 with (contact adj hole via) with temperature near2 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:21 |
| S58 | 5 | etch\$3 with (contact adj hole via) with temperature near4 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 18:58 |
| S59 | 3 | S58 not S57 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 18:58 |
| S60 | 59 | etch\$3 with (contact adj hole via) with temperature with bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 18:58 |

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| S61 | 9 | etch\$3 with (contact adj hole via) with temperature near6 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:03 |
| S62 | 4 | S61 not S58 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:03 |
| S63 | 17 | etch\$3 with (contact adj hole via) with temperature near8 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:05 |
| S64 | 8 | S63 not S61 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:03 |
| S65 | 21 | etch\$3 with (contact adj hole via) with temperature near10 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:07 |
| S66 | 4 | S65 not S63 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:05 |

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| S67 | 39 | etch\$3 with (contact adj hole via) with temperature near15 bottom | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:07 |
| S68 | 18 | S67 not S65 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:17 |
| S69 | 20 | S60 not S67 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:17 |
| S70 | 1 | etch\$3 with (contact adj hole via) with temperature near2 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:21 |
| S71 | 9 | etch\$3 with (contact adj hole via) with temperature near4 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:24 |
| S72 | 8 | S71 not S70 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:22 |

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| S73 | 13 | etch\$3 with (contact adj hole via) with temperature near6 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:25 |
| S74 | 4 | S73 not S71 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:25 |
| S75 | 13 | etch\$3 with (contact adj hole via) with temperature near8 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:25 |
| S76 | 16 | etch\$3 with (contact adj hole via) with temperature near10 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:26 |
| S77 | 21 | etch\$3 with (contact adj hole via) with temperature near12 sidewall | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:26 |
| S78 | 8 | S77 not S75 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/23 19:26 |

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| S79 | 1152 | (contact adj hole via) with temperature with (gradient profile) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/24 12:46 |
| S80 | 721 | (contact adj hole via) with temperature near (gradient profile) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/24 12:45 |
| S81 | 93 | S80 and etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/24 12:46 |
| S82 | 25 | contact adj hole with temperature with (gradient profile) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/24 12:46 |
| S83 | 945 | (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") with etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 06:11 |
| S84 | 882 | (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") with etch\$3 | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:43 |
| S85 | 352 | (N2 "N.sub.2" nitrogen) near2 (CF4 "CF.sub.4") with etch\$3 | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:43 |

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| S86 | 187 | (N2 "N.sub.2" nitrogen) near (CF4 "CF.sub.4") with etch\$3 | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:43 |
| S87 | 111 | S86 and etch\$3 near (oxide silicon SiO2 "SiO.sub.2" SiO2 "SiO.sub.2") | US-PGPUB; USPAT | OR | ON | 2005/10/19 18:01 |
| S88 | 36 | S86 same etch\$3 near (oxide silicon SiO2 "SiO.sub.2" SiO2 "SiO.sub.2") | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:45 |
| S89 | 25 | S86 with etch\$3 near (oxide silicon SiO2 "SiO.sub.2" SiO2 "SiO.sub.2") | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:45 |
| S90 | 11 | S88 not S89 | US-PGPUB; USPAT | OR | ON | 2005/10/19 17:57 |
| S91 | 18 | S87 and ratio with ((N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2005/10/19 18:06 |
| S92 | 11 | S86 and ratio with ((N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4")) not S91 | US-PGPUB; USPAT | OR | ON | 2005/10/19 18:12 |
| S93 | 15 | S85 and ratio with ((N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4")) not (S91 S92) | US-PGPUB; USPAT | OR | ON | 2005/10/19 18:12 |
| S94 | 63 | (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") with etch\$3 | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/20 20:37 |
| S95 | 2 | (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") with etch\$3 and (TEOS BCB polysiloxane) | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/20 20:15 |

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| S96 | 8 | polysiloxane with (SiO ₂ "SiO.sub.2" SiO ₂ "SiO.sub.2" silicon adj \$2oxide) same etch\$3 | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/20 20:33 |
| S97 | 27 | polysiloxane with (SiO ₂ "SiO.sub.2" SiO ₂ "SiO.sub.2" silicon adj \$2oxide) same etch\$3 | US-PGPUB; USPAT | OR | ON | 2005/10/20 20:33 |
| S98 | 17 | (N ₂ "N.sub.2" nitrogen CF ₄ "CF.sub.4") and polysiloxane with (SiO ₂ "SiO.sub.2" SiO ₂ "SiO.sub.2" silicon adj \$2oxide) same etch\$3 | US-PGPUB; USPAT | OR | ON | 2005/10/20 20:37 |
| S99 | 8 | (US-6060400-\$ or US-6136211-\$ or US-6143665-\$ or US-6325861-\$ or US-6355567-\$).did. or (WO-9933096-\$).did. or (JP-11145114-\$).did. or (US-5854119-\$).did. | USPAT; EPO; JPO; DERWENT | OR | ON | 2005/10/21 06:11 |
| S100 | 8 | S99 and ((N ₂ "N.sub.2" nitrogen) same (CF ₄ "CF.sub.4") same etch \$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 06:12 |
| S101 | 5 | plasma and ((N ₂ "N.sub.2" nitrogen) with (damag\$3) near (interior chamber reactor)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:09 |

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| S102 | 7025 | plasma and ((N2 "N.sub.2" nitrogen) with (react\$3 damag \$3) with (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:10 |
| S103 | 1638 | plasma and ((N2 "N.sub.2" nitrogen) near3 (react\$3 damag \$3) near3 (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:10 |
| S104 | 842 | plasma and ((N2 "N.sub.2" nitrogen) near2 (react\$3 damag \$3) near2 (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:11 |
| S105 | 189 | plasma and ((N2 "N.sub.2" nitrogen) near (react\$3 damag \$3) near (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:11 |
| S106 | 36 | plasma same ((N2 "N.sub.2" nitrogen) near (react\$3 damag \$3) near (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:11 |
| S107 | 28 | plasma with ((N2 "N.sub.2" nitrogen) near (react\$3 damag \$3) near (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:11 |

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| S108 | 4 | plasma near ((N2 "N.sub.2" nitrogen) near (react\$3 damag \$3) near (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:12 |
| S109 | 12 | plasma near3 ((N2 "N.sub.2" nitrogen) near (react\$3 damag \$3) near (component interior chamber reactor)) not S101 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:13 |
| S110 | 3 | S109 not S108 | US-PGPUB; USPAT | OR | ON | 2005/10/21 17:17 |
| S111 | 8 | S107 not S109 | US-PGPUB; USPAT | OR | ON | 2005/10/21 17:16 |
| S112 | 5 | S106 not S107 | US-PGPUB; USPAT | OR | ON | 2005/10/21 17:16 |
| S113 | 5 | S109 not (S108 S110) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:18 |
| S114 | 8 | S107 not (S109 S111) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:20 |

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| S115 | 3 | S106 not (S107 S112) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:20 |
| S116 | 0 | more adj (N2 "N.sub.2" nitrogen) near (CF4 "CF.sub.4") same etch \$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:54 |
| S117 | 1 | more adj (N2 "N.sub.2" nitrogen) near4 (CF4 "CF.sub.4") same etch \$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:54 |
| S118 | 2 | (greater more higher) near (N2 "N.sub.2" nitrogen) near4 (CF4 "CF.sub.4") same etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:55 |
| S119 | 32 | (greater more higher) near2 (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") same etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 17:58 |
| S120 | 23 | ratio near2 (N2 "N.sub.2" nitrogen) near2 (CF4 "CF.sub.4") same etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 18:04 |

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| S121 | 2 | flow adj ratio near4 (N2 "N.sub.2" nitrogen) near4 (CF4 "CF.sub.4") same etch\$3 not S120 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 18:22 |
| S122 | 1 | flow adj ratio with (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") same etch\$3 not (S120 "22") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 18:23 |
| S123 | 1 | flow near ratio with (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") same etch\$3 not (S120 "22") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 18:23 |
| S124 | 13 | ratio with (N2 "N.sub.2" nitrogen) with (CF4 "CF.sub.4") same etch\$3 not (S120 "22") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 18:24 |
| S125 | 1 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass) with polysiloxane with structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:12 |
| S126 | 25 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass) with polysiloxane same structure | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:17 |

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| S127 | 9 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass) same polysiloxane same structure not S126 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:19 |
| S128 | 1156 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) near structure not S126 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:19 |
| S129 | 776 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) adj structure not S126 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:19 |
| S130 | 10 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) adj chemical adj structure not S126 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:22 |
| S131 | 10 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) near chemical adj structure not S126 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:22 |
| S132 | 0 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) near chemical adj structure not (S126 S130) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:22 |

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| S133 | 93 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) with chemical adj structure not (S126 S130) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:22 |
| S134 | 17 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) near4 chemical adj structure not (S126 S130) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:24 |
| S135 | 11 | (tetraethylorthosilane teos sog "spin-on-glass" spin near glass polysiloxane) near6 chemical adj structure not (S126 S130 S134) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:26 |
| S136 | 65 | S133 not (S126 S130 S134 S135) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:33 |
| S137 | 4 | polysiloxane adj (film layer) with (SiO2 "SiO.sub.2" SiO2 "SiO.sub.2" silicon adj \$2oxide) with etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:35 |
| S138 | 9 | polysiloxane adj (film layer) with (SiO2 "SiO.sub.2" SiO2 "SiO.sub.2" silicon adj \$2oxide) same etch\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/21 19:38 |

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| S139 | 1 | ("6284149").PN. | USPAT | OR | OFF | 2006/03/24 12:35 |
| S140 | 137 | (etch\$4 same (N2 "N.sub.2") with (CF4 "CF.sub.4")) and (etch \$4 same (oxide SiO2 "SiO. sub.2")) and ((etch\$4 adj stop\$4 etchstop) with (oxide SiO2 "SiO. sub.2")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:44 |
| S141 | 69 | S140 and (silsesquioxane HSQ orthosilicate TEOS silane BCB Silk Flare polysiloxane siloxane (si silicon) near organic) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:46 |
| S142 | 8 | S140 and BCB | US-PGPUB; USPAT | OR | ON | 2006/03/24 14:37 |
| S143 | 6 | S140 and (Silk Flare) | US-PGPUB; USPAT | OR | ON | 2006/03/24 14:43 |
| S144 | 10 | S140 and ((si silicon si- containing silicon-containing) near3 organic) | US-PGPUB; USPAT | OR | ON | 2006/03/24 15:05 |
| S145 | 52 | S141 not (S142 S143 S144) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:45 |
| S146 | 118 | (etch\$4 with (N2 "N.sub.2") with (CF4 "CF.sub.4")) and (etch\$4 with (oxide SiO2 "SiO.sub.2")) and ((etch\$4 adj stop\$4 etchstop) with (oxide SiO2 "SiO. sub.2")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:23 |

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| S147 | 51 | (etch\$4 with (N2 "N.sub.2") with (CF4 "CF.sub.4")) and (etch\$4 with (oxide SiO2 "SiO.sub.2")) and ((etch\$4 adj stop\$4 etchstop) near3 (oxide SiO2 "SiO.sub.2")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:44 |
| S148 | 31 | S147 not S141 | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:24 |
| S149 | 36 | S140 not (S141 S142 S143 S144 S147) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:53 |
| S150 | 34 | S146 not (S141 S142 S143 S144 S147) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:57 |
| S151 | 0 | S146 not (S140 S141 S142 S143 S144 S147) | US-PGPUB; USPAT | OR | ON | 2006/03/24 17:53 |
| S152 | 59 | (etch\$4 with (N2 "N.sub.2") near2 (CF4 "CF.sub.4")) and (etch\$4 with (oxide SiO2 "SiO.sub.2")) and ((etch\$4 adj stop\$4 etchstop) with (oxide SiO2 "SiO.sub.2")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:45 |
| S153 | 26 | (etch\$4 with (N2 "N.sub.2") near2 (CF4 "CF.sub.4")) and (etch\$4 near3 (oxide SiO2 "SiO.sub.2")) and ((etch\$4 adj stop\$4 etchstop) near3 (oxide SiO2 "SiO.sub.2")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:45 |

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| S154 | 13 | S153 and (coral hosp silsesquioxane HSQ orthosilicate TEOS silane BCB Silk Flare polysiloxane siloxane (si silicon) near organic) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:51 |
| S155 | 0 | etch\$3 with BCB with ((C4F8 "C. sub.4 F.sub.8") with (CF4 "CF. sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:52 |
| S156 | 1 | etch\$4 same BCB same ((C4F8 "C.sub.4 F.sub.8") same (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:53 |
| S157 | 51 | etch\$4 and BCB and ((C4F8 "C. sub.4 F.sub.8") same (CF4 "CF. sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:56 |
| S158 | 1 | etch\$4 and BCB same ((C4F8 "C. sub.4 F.sub.8") same (CF4 "CF. sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:20 |
| S159 | 45 | etch\$4 and BCB and ((C4F8 "C. sub.4 F.sub.8") with (CF4 "CF. sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:54 |
| S160 | 0 | etch\$4 and ((C4F8 "C.sub.4 F. sub.8") with (CF4 "CF.sub.4")) same BCB | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:54 |
| S161 | 44 | etch\$4 same ((C4F8 "C.sub.4 F. sub.8") with (CF4 "CF.sub.4")) and BCB | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:55 |
| S162 | 0 | etch\$4 same ((C4F8 "C.sub.4 F. sub.8") with (CF4 "CF.sub.4")) same BCB | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:55 |

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| S163 | 26 | etch\$4 same ((C4F8 "C.sub.4 F.sub.8") near3 (CF4 "CF.sub.4")) and bcb | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:57 |
| S164 | 39 | etch\$4 and BCB and ((C4F8 "C.sub.4 F.sub.8") same (CF4 "CF.sub.4")) and (N2 "N.sub.2") | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:56 |
| S165 | 5 | etch\$4 same ((C4F8 "C.sub.4 F.sub.8") near3 (CF4 "CF.sub.4") same (N2 "N.sub.2")) and bcb | US-PGPUB; USPAT | OR | ON | 2006/03/24 18:58 |
| S166 | 34 | S164 not S165 | US-PGPUB; USPAT | OR | ON | 2006/03/24 20:49 |
| S167 | 21 | S163 not S165 | US-PGPUB; USPAT | OR | ON | 2006/03/24 20:16 |
| S168 | 43 | bcb near dielectric adj constant | US-PGPUB; USPAT | OR | ON | 2006/03/24 20:17 |
| S169 | 43 | bcb adj dielectric adj constant | US-PGPUB; USPAT | OR | ON | 2006/03/24 20:17 |
| S170 | 14 | S166 not S167 | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:01 |
| S171 | 11 | S157 not (S164 S166 S167 S170) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:03 |
| S172 | 0 | etch\$4 with (benzocyclobutene cyclotene BCB) and ethc\$4 same ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:21 |
| S173 | 7 | etch\$4 with (benzocyclobutene cyclotene BCB) and etch\$4 same ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:24 |

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| S174 | 7 | etch\$4 with (benzocyclobutene cyclotene BCB) and ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S175 | 49 | etch\$4 and (benzocyclobutene cyclotene BCB) and ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S176 | 0 | etch\$4 and (benzocyclobutene cyclotene BCB) same ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S177 | 0 | etch\$4 same (benzocyclobutene cyclotene BCB) same ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S178 | 14 | etch\$4 same (benzocyclobutene cyclotene BCB) and ((C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4")) | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S179 | 0 | S178 not S175 | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S180 | 7 | S178 not S174 | US-PGPUB; USPAT | OR | ON | 2006/03/24 21:25 |
| S181 | 0 | etch\$4 with (polysiloxane BCB FLARE) with (C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4") | US-PGPUB; USPAT | OR | ON | 2006/03/27 13:05 |
| S182 | 0 | etch\$4 with (polysiloxane BCB FLARE) with (C4F8 "C.sub.4 F.sub.8") with (CF4 "CF.sub.4") | EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:05 |

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| S183 | 1 | etch\$4 same (polysiloxane BCB FLARE) same (C4F8 "C.sub.4 F. sub.8") same (CF4 "CF.sub.4") | US-PGPUB; USPAT | OR | ON | 2006/03/27 13:06 |
| S184 | 1 | etch\$4 same (polysiloxane BCB FLARE) same (C4F8 "C.sub.4 F. sub.8") same (CF4 "CF.sub.4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:06 |
| S185 | 26 | etch\$4 same (polysiloxane BCB FLARE) and (C4F8 "C.sub.4 F. sub.8") same (CF4 "CF.sub.4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:39 |
| S186 | 16 | etch\$4 with (polysiloxane BCB FLARE) and (C4F8 "C.sub.4 F. sub.8") same (CF4 "CF.sub.4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:19 |
| S187 | 10 | S185 not S186 | US-PGPUB; USPAT | OR | ON | 2006/03/27 13:19 |
| S188 | 20 | etch\$4 same (polysiloxane BCB FLARE) same (CF4 "CF.sub.4") same (N2 "N.sub.2") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:28 |
| S189 | 54 | etch\$4 same (polysiloxane BCB FLARE) and etch\$4 same (CF4 "CF.sub.4") same (N2 "N.sub.2") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:37 |

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| S190 | 34 | S189 not S188 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:28 |
| S191 | 3 | etch\$4 same (polysiloxane BCB FLARE) and etch\$4 same (\$5fluoromethane) same (N2 "N.sub.2") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:38 |
| S192 | 28 | etch\$4 same (polysiloxane BCB FLARE) and (C4F8 "C.sub.4 F.sub.8" perfluorocyclobutane octafluorocyclobutane perfluoro \$3butene octafluoro\$3butene) same (CF4 "CF.sub.4" perfluoromethane tetrafluoromethane) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:49 |
| S193 | 57 | S192 not 5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:42 |
| S194 | 2 | S192 not S185 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:43 |

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| S195 | 657 | etch\$4 same (C4F8 "C.sub.4 F. sub.8" perfluorocyclobutane octafluorocyclobutane perfluoro \$3butene octafluoro\$3butene) with (CF4 "CF.sub.4" perfluoromethane tetrafluoromethane) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 13:50 |
| S196 | 78 | etch\$4 same (C4F8 "C.sub.4 F. sub.8" perfluorocyclobutane octafluorocyclobutane perfluoro \$3butene octafluoro\$3butene) with (CF4 "CF.sub.4" perfluoromethane tetrafluoromethane) with (N2 "N. sub.2") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 14:17 |
| S197 | 21 | (US-6720249-\$ or US-6472717-\$ or US-6455411-\$ or US-6440864- \$ or US-6326307-\$ or US- 6284642-\$ or US-6211051-\$ or US-6180975-\$ or US-6177329-\$ or US-6163407-\$ or US-6159661- \$ or US-6143665-\$ or US- 6040223-\$ or US-6033979-\$ or US-6014979-\$ or US-5990015-\$ or US-5972789-\$ or US-5801094- \$ or US-5654233-\$ or US- 5038713-\$).did. or (JP-11145114- \$).did. | USPAT; JPO | OR | ON | 2006/03/27 14:16 |
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|------|------|--|---|----|-----|---------------------|
| S198 | 21 | S197 and (C4F8 "C.sub.4 F. sub.8" perfluorocyclobutane octafluorocyclobutane perfluoro \$3butene octafluoro\$3butene CF4 "CF.sub.4" perfluoromethane tetrafluoromethane N2 "N.sub.2" polysiloxane BCB FLARE) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 14:28 |
| S199 | 8 | S198 and (polysiloxane BCB FLARE (((si silicon) adj containing) silicon-containing si-containing) near (low-k low adj dielectric) organic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 14:33 |
| S200 | 1 | S198 and (polysiloxane BCB FLARE (((si silicon) adj containing) silicon-containing si-containing) near (low-k low adj dielectric organic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/27 14:33 |
| S201 | 1 | ("6506680").PN. | USPAT | OR | OFF | 2007/05/14 12:21 |
| S202 | 1 | S201 and select\$6 | US-PGPUB; USPAT | OR | ON | 2007/05/14 12:22 |
| S203 | 1570 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) and selectiv\$6 and (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/10/10 08:25 |

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|------|------|---|-----------------|----|----|------------------|
| S204 | 1026 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) and selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 12:35 |
| S205 | 632 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) and selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 12:35 |
| S206 | 522 | etch\$4 with (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) and selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 12:35 |
| S207 | 98 | etch\$4 with (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 12:36 |
| S208 | 53 | S207 and organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:10 |
| S209 | 98 | etch\$4 with (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:44 |
| S210 | 53 | S209 and organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:11 |

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|------|------|---|--------------------|----|----|---------------------|
| S211 | 45 | S209 not S210 | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:11 |
| S212 | 115 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:50 |
| S213 | 17 | S212 not S209 | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:44 |
| S214 | 211 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 14:02 |
| S215 | 96 | S214 not S212 | US-PGPUB; USPAT | OR | ON | 2007/05/14 13:51 |
| S216 | 18 | S215 and etch\$4 with organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 14:03 |
| S217 | 1026 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) and selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 14:02 |
| S218 | 296 | S217 not S214 and etch\$4 with organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 14:03 |
| S219 | 139 | S217 not S214 and organic near (etch\$4 dielectric ILD low-k) | US-PGPUB; USPAT | OR | ON | 2007/05/14 14:07 |

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|------|------|---|--------------------|----|----|---------------------|
| S220 | 11 | (US-20010010970-\$).did. or (US-6143665-\$ or US-6107155-\$ or US-6316160-\$ or US-6475918-\$ or US-6309962-\$ or US-6211061-\$ or US-6570257-\$ or US-6410437-\$ or US-6319815-\$ or US-6168726-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:21 |
| S221 | 211 | etch\$4 same (((C4F8 "C.sub.4 F.sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:21 |
| S222 | 1026 | etch\$4 same (((C4F8 "C.sub.4 F.sub.8") (CF4 "CF.sub.4")) same (N2 "N.sub.2" nitrogen)) and selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:21 |
| S223 | 139 | S222 not S221 and organic near (etch\$4 dielectric ILD low-k) | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:21 |
| S224 | 8 | S220 and S223 | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:22 |
| S225 | 3 | S220 and S221 | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:22 |
| S226 | 11 | S224 S225 | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:27 |
| S227 | 0 | S226 and polysiloxane | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:28 |

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|------|----|--|--------------------|----|----|---------------------|
| S228 | 98 | etch\$4 with (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/10/10 05:56 |
| S229 | 53 | S228 and organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:28 |
| S230 | 5 | S229 and polysiloxane | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:28 |
| S231 | 16 | (US-20060166485-\$ or US-20010010970-\$ or US-20010009803-\$).did. or (US-6143665-\$ or US-6107155-\$ or US-6316160-\$ or US-6475918-\$ or US-7060605-\$ or US-6909190-\$ or US-6309962-\$ or US-6211061-\$ or US-6570257-\$ or US-6410437-\$ or US-6319815-\$ or US-6316351-\$ or US-6168726-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:29 |
| S232 | 4 | (US-6326307-\$ or US-6455411-\$ or US-6872665-\$ or US-6686296-\$).did. | USPAT | OR | ON | 2007/05/14 15:29 |

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|------|----|--|--|----|----|---------------------|
| S233 | 33 | (US-20020058362-\$).did. or (US-6143665-\$ or US-5801094-\$ or US-6211051-\$ or US-6342449-\$ or US-6319815-\$ or US-6284149-\$ or US-6211035-\$ or US-6326307-\$ or US-6060400-\$ or US-6440864-\$ or US-6720249-\$ or US-6177329-\$ or US-6221745-\$ or US-6284642-\$ or US-6180975-\$ or US-6015751-\$ or US-5204276-\$ or US-6737350-\$ or US-6573196-\$ or US-6472717-\$ or US-6455411-\$ or US-6159661-\$ or US-6040223-\$ or US-6033979-\$ or US-5990015-\$ or US-5972789-\$).did. or (US-6180518-\$ or US-6163407-\$ or US-6014979-\$ or US-5654233-\$ or US-5038713-\$).did. or (JP-11145114-\$).did. | US-PGPUB; USPAT; JPO | OR | ON | 2007/05/14 15:29 |
| S234 | 10 | (US-20050090634-\$).did. or (US-6143665-\$ or US-6325861-\$ or US-6136211-\$ or US-6060400-\$ or US-6355567-\$ or US-4976818-\$).did. or (WO-9933096-\$).did. or (JP-11145114-\$).did. or (US-5854119-\$).did. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2007/05/14 15:30 |

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|------|-----|--|---|----|----|---------------------|
| S235 | 24 | (US-20020195419-\$ or US-20020074309-\$ or US-20010027016-\$).did. or (US-5835987-\$ or US-6461962-\$ or US-6331380-\$ or US-6168726-\$ or US-6245489-\$ or US-5604380-\$ or US-6340435-\$ or US-6281135-\$ or US-6255180-\$ or US-5658425-\$ or US-5522957-\$ or US-5173151-\$ or US-6235453-\$ or US-6417090-\$ or US-6153514-\$ or US-6472317-\$ or US-5721156-\$ or US-6051153-\$ or US-5605600-\$ or US-6376386-\$ or US-6617253-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:30 |
| S236 | 3 | (S231 S232 S233 S234 S235) and polysiloxane | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:38 |
| S237 | 5 | S230 not S236 | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:33 |
| S238 | 115 | etch\$4 same (((C4F8 "C.sub.4 F. sub.8") (CF4 "CF.sub.4")) with (N2 "N.sub.2" nitrogen)) same selectiv\$6 same (photoresist resist) | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:38 |

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|------|-----|---|---|----|----|---------------------|
| S239 | 5 | S238 and polysiloxane | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:40 |
| S240 | 0 | S239 not S230 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:39 |
| S241 | 5 | S221 and polysiloxane | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:40 |
| S242 | 296 | S222 not S221 and etch\$4 with organic | US-PGPUB; USPAT | OR | ON | 2007/05/14 15:40 |
| S243 | 13 | S242 and polysiloxane | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:40 |

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| S244 | 13 | S243 not (S236 S237) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/14 15:41 |
| S245 | 2 | ("6352931").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2007/05/14 16:51 |
| S246 | 1 | etch\$4 with polysiloxane with ((CF4 "CF.sub.4") with (N2 "N. sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 09:33 |
| S247 | 6 | etch\$4 same polysiloxane same ((CF4 "CF.sub.4") same (N2 "N. sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:01 |
| S248 | 12 | etch\$4 same polysiloxane and ((CF4 "CF.sub.4") same (N2 "N. sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:04 |
| S249 | 6 | S248 not S247 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:01 |
| S250 | 40 | etch\$4 same polysiloxane and ((CF4 "CF.sub.4") and (N2 "N. sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:09 |
| S251 | 28 | S250 not S248 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:04 |
| S252 | 174 | etch\$4 and polysiloxane and ((CF4 "CF.sub.4") and (N2 "N. sub.2" nitrogen)) not S250 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:10 |

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| S253 | 44 | etch\$4 and polysiloxane and ((CF4 "CF.sub.4") same (N2 "N.sub.2" nitrogen)) not S250 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:31 |
| S254 | 20 | etch\$4 and polysiloxane and ((CF4 "CF.sub.4") with (N2 "N.sub.2" nitrogen)) not S250 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:22 |
| S255 | 24 | S253 not S254 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:22 |
| S256 | 0 | etch\$4 and polysiloxane same ((CF4 "CF.sub.4") and (N2 "N.sub.2" nitrogen)) not S250 | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:31 |
| S257 | 6 | etch\$4 and polysiloxane same ((CF4 "CF.sub.4") and (N2 "N.sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 06:31 |
| S258 | 310 | etch\$4 same (C4F8 "C.sub.4 F.sub.8") same (N2 "N.sub.2" nitrogen) | US-PGPUB; USPAT | OR | ON | 2007/10/10 08:26 |
| S259 | 183 | etch\$4 same (C4F8 "C.sub.4 F.sub.8") with (N2 "N.sub.2" nitrogen) | US-PGPUB; USPAT | OR | ON | 2007/10/10 08:26 |
| S260 | 145 | etch\$4 with (C4F8 "C.sub.4 F.sub.8") with (N2 "N.sub.2" nitrogen) | US-PGPUB; USPAT | OR | ON | 2007/10/10 08:26 |
| S261 | 27 | etch\$4 with (C4F8 "C.sub.4 F.sub.8") with (N2 "N.sub.2" nitrogen) same ratio | US-PGPUB; USPAT | OR | ON | 2007/10/10 08:26 |

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|------|----|--|--------------------|----|----|---------------------|
| S262 | 46 | etch\$4 with (O-BARC O-BARL org-BARC org-BARL BCB O-SOG organic) with ((CF4 "CF.sub.4") with (N2 "N.sub.2" nitrogen)) | US-PGPUB; USPAT | OR | ON | 2007/10/10 09:36 |
| S263 | 1 | (US-6355572-\$).did. | USPAT | OR | ON | 2007/10/10 09:52 |
| S264 | 1 | S263 and (ar argon) | USPAT | OR | ON | 2007/10/10 09:53 |
| S265 | 1 | S263 | USPAT | OR | ON | 2007/10/10 11:24 |
| S266 | 7 | ("5262358" "5721156" "5835987" "6410437" "6455411" "6506680" "6570257").PN. | USPAT | OR | ON | 2007/10/10 11:30 |
| S267 | 24 | (US-20020195419-\$ or US- 20020074309-\$ or US- 20010027016-\$).did. or (US- 6245489-\$ or US-5604380-\$ or US-6340435-\$ or US-6281135-\$ or US-6255180-\$ or US-5658425- \$ or US-5173151-\$ or US- 5522957-\$ or US-6235453-\$ or US-6168726-\$ or US-6472317-\$ or US-6417090-\$ or US-6331380- \$ or US-5721156-\$ or US- 6153514-\$ or US-5835987-\$ or US-6461962-\$ or US-6051153-\$ or US-5605600-\$ or US-6376386- \$ or US-6617253-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:25 |

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|------|----|--|--|----|----|---------------------|
| S268 | 10 | (US-20050090634-\$).did. or (US-6325861-\$ or US-6143665-\$ or US-6136211-\$ or US-6060400-\$ or US-6355567-\$ or US-4976818-\$).did. or (WO-9933096-\$).did. or (JP-11145114-\$).did. or (US-5854119-\$).did. | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2007/10/10 11:25 |
| S269 | 33 | (US-20020058362-\$).did. or (US-6284149-\$ or US-6143665-\$ or US-6060400-\$ or US-6326307-\$ or US-6440864-\$ or US-6221745-\$ or US-5801094-\$ or US-6720249-\$ or US-6342449-\$ or US-6319815-\$ or US-6211035-\$ or US-6177329-\$ or US-6284642-\$ or US-6180975-\$ or US-5204276-\$ or US-6015751-\$ or US-6737350-\$ or US-6573196-\$ or US-6180518-\$ or US-6033979-\$ or US-6014979-\$ or US-5972789-\$ or US-5654233-\$ or US-6455411-\$ or US-6472717-\$ or US-6040223-\$).did. or (US-6211051-\$ or US-6163407-\$ or US-6159661-\$ or US-5990015-\$ or US-5038713-\$).did. or (JP-11145114-\$).did. | US-PGPUB; USPAT; JPO | OR | ON | 2007/10/10 11:25 |
| S270 | 4 | (US-6326307-\$ or US-6455411-\$ or US-6872665-\$ or US-6686296-\$).did. | USPAT | OR | ON | 2007/10/10 11:26 |

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|------|----|--|--------------------|----|----|---------------------|
| S271 | 16 | (US-20010010970-\$ or US-20010009803-\$ or US-20060166485-\$).did. or (US-6211061-\$ or US-6168726-\$ or US-6309962-\$ or US-6143665-\$ or US-6107155-\$ or US-6319815-\$ or US-6909190-\$ or US-6316160-\$ or US-7060605-\$ or US-6570257-\$ or US-6410437-\$ or US-6316351-\$ or US-6475918-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:26 |
| S272 | 11 | (US-20010010970-\$).did. or (US-6211061-\$ or US-6168726-\$ or US-6309962-\$ or US-6143665-\$ or US-6107155-\$ or US-6319815-\$ or US-6316160-\$ or US-6570257-\$ or US-6410437-\$ or US-6475918-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:26 |
| S273 | 16 | (US-20060231525-\$ or US-20040050816-\$ or US-20030222048-\$ or US-20050079717-\$ or US-20040092111-\$ or US-20020094695-\$).did. or (US-7097781-\$ or US-7090784-\$ or US-6565763-\$ or US-6805139-\$ or US-6570257-\$ or US-6316351-\$ or US-6284642-\$ or US-6284149-\$ or US-6355572-\$ or US-6013547-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:26 |

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| S274 | 88 | S267 S268 S269 S270 S271 S272 S273 | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:26 |
| S275 | 83 | S274 not S266 | US-PGPUB; USPAT | OR | ON | 2007/10/10 11:27 |
| S276 | 0 | polysiloxane adj TEOS | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/29 18:34 |
| S277 | 0 | polysiloxane near TEOS | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/29 18:34 |
| S278 | 58 | polysiloxane with TEOS | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/03/29 18:35 |
| S279 | 2 | ("6251770").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/03/29 19:19 |
| S280 | 28 | dielectric adj constant near TEOS | US-PGPUB; USPAT | OR | ON | 2008/03/29 19:58 |
| S281 | 1 | ("7419902").PN. | USPAT | OR | OFF | 2009/02/03 10:55 |
| S282 | 1 | S281 and (CF4 "CF.sub.4") | US-PGPUB; USPAT | OR | ON | 2009/02/03 11:01 |

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| S283 | 0 | 10-265526 | JPO; DERWENT | OR | ON | 2009/02/03 11:03 |
| S284 | 35 | "265526" | JPO; DERWENT | OR | ON | 2009/02/03 11:03 |
| S285 | 2 | S284 and toshiba | JPO; DERWENT | OR | ON | 2009/02/03 11:03 |
| S286 | 4 | "2001068455" | JPO; DERWENT | OR | ON | 2009/02/03 11:04 |
| S287 | 1 | 2001-278484.NRAN. | DERWENT | OR | ON | 2009/02/03 11:07 |
| S288 | 2 | "10265526" | JPO; DERWENT | OR | ON | 2009/02/03 11:11 |
| S289 | 1 | 1998-589740.NRAN. | DERWENT | OR | ON | 2009/02/03 11:11 |
| S290 | 2 | ((("5658425") or ("6284149")). PN. | USPAT | OR | OFF | 2009/02/04 15:03 |
| S291 | 3687 | (n2 "n.sub.2" nitrogen adj gas). drwd. | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:31 |
| S292 | 74579 | rate\$4.drwd. | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:31 |
| S293 | 851 | S291 and S292 | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:31 |
| S294 | 183 | S293 and ("216"/\$.ccls. "438"/\$. ccls.) | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:32 |
| S295 | 66 | S294 and @ad<"19991026" | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:33 |
| S296 | 21 | S295 and (CF4 "CF.sub.4") | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:33 |

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| S297 | 6 | S296 and (CF ₄ "CF.sub.4") with (n ₂ "n.sub.2" nitrogen adj gas) | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:34 |
| S298 | 3 | S295 and tetrafluoride not S297 | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:38 |
| S299 | 1 | S295 and tetrafluoride not S296 | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:38 |
| S300 | 1 | S295 and (fluorcarbon hydrofluorocarbon) not S296 | US-PGPUB; USPAT | OR | ON | 2009/04/14 16:41 |
| S301 | 846 | (CF ₄ "CF.sub.4") with (N ₂ "N.sub.2") with (Ar argon) same etch\$4 | US-PGPUB; USPAT | OR | ON | 2009/06/19 14:02 |
| S302 | 156 | (CF ₄ "CF.sub.4") near ₂ (N ₂ "N.sub.2") near ₂ (Ar argon) same etch\$4 | US-PGPUB; USPAT | OR | ON | 2009/06/19 14:03 |
| S303 | 54 | (CF ₄ "CF.sub.4") near (N ₂ "N.sub.2") near (Ar argon) same etch\$4 | US-PGPUB; USPAT | OR | ON | 2009/06/19 14:03 |
| S304 | 41 | (CF ₄ "CF.sub.4") near (N ₂ "N.sub.2") near (Ar argon) WITH etch\$4 | US-PGPUB; USPAT | OR | ON | 2009/06/19 14:03 |

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